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2SC1509

Silicon NPN epitaxial planar type

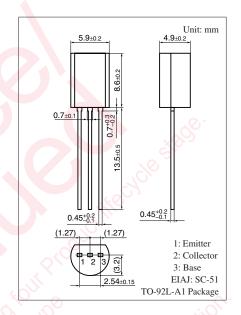
For low-frequency driver amplification Complementary to 2SA0777 (2SA777)

■ Features

- High collector-emitter voltage (Base open) V_{CEO}
- Optimum for the driver stage of a low-frequency and 25 W to 30 W output amplifier

■ Absolute Maximum Ratings $T_a = 25$ °C

Symbol	Rating	Unit
V_{CBO}	80	V
V_{CEO}	80	V
V _{EBO}	5	V
I_{C}	0.5	A
I_{CP}	1	A
P _C	750	mW
T_{j}	150	°C
T _{stg}	-55 to +150	°C O
	$\begin{array}{c} V_{CBO} \\ V_{CEO} \\ V_{EBO} \\ I_{C} \\ I_{CP} \\ P_{C} \\ T_{j} \end{array}$	VCBO 80 VCEO 80 VEBO 5 IC 0.5 ICP 1 PC 750 Tj 150



■ Electrical Characteristics T_a = 25°C ± 3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_C = 10 \mu\text{A}, I_E = 0$	80	0.		V
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = 100 \mu\text{A}, I_B = 0$	80			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10 \mu A, I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 20 \text{ V}, I_{E} = 0$			0.1	μΑ
Forward current transfer ratio	h _{FE1} *	$V_{CE} = 10 \text{ V}, I_{C} = 150 \text{ mA}$	130		330	_
	h _{FE2}	$V_{CE} = 5 \text{ V}, I_{C} = 500 \text{ mA}$	50	100		_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 300 \text{ mA}, I_B = 30 \text{ mA}$		0.2	0.4	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_C = 300 \text{ mA}, I_B = 30 \text{ mA}$		0.85	1.2	V
Transition frequency	f_T	$V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		120		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		11	20	pF

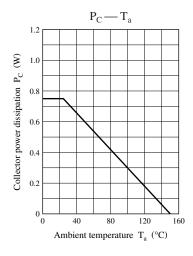
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

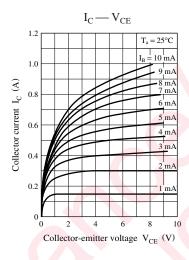
2. *: Rank classification

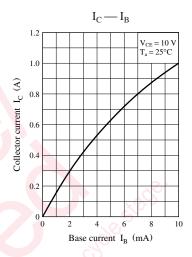
Rank	R	S
h _{FE1}	130 to 220	185 to 330

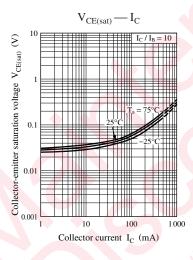
Note) The part number in the parenthesis shows conventional part number.

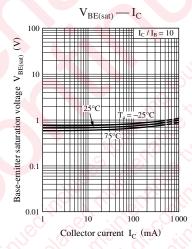
Panasonic

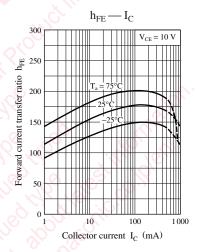


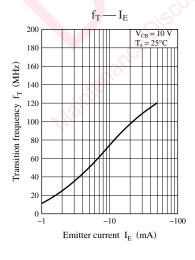


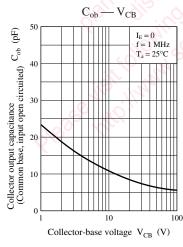


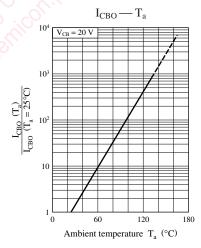




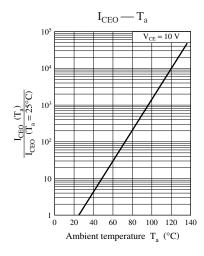


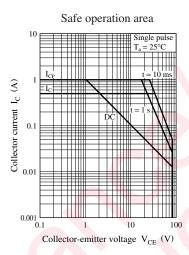






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